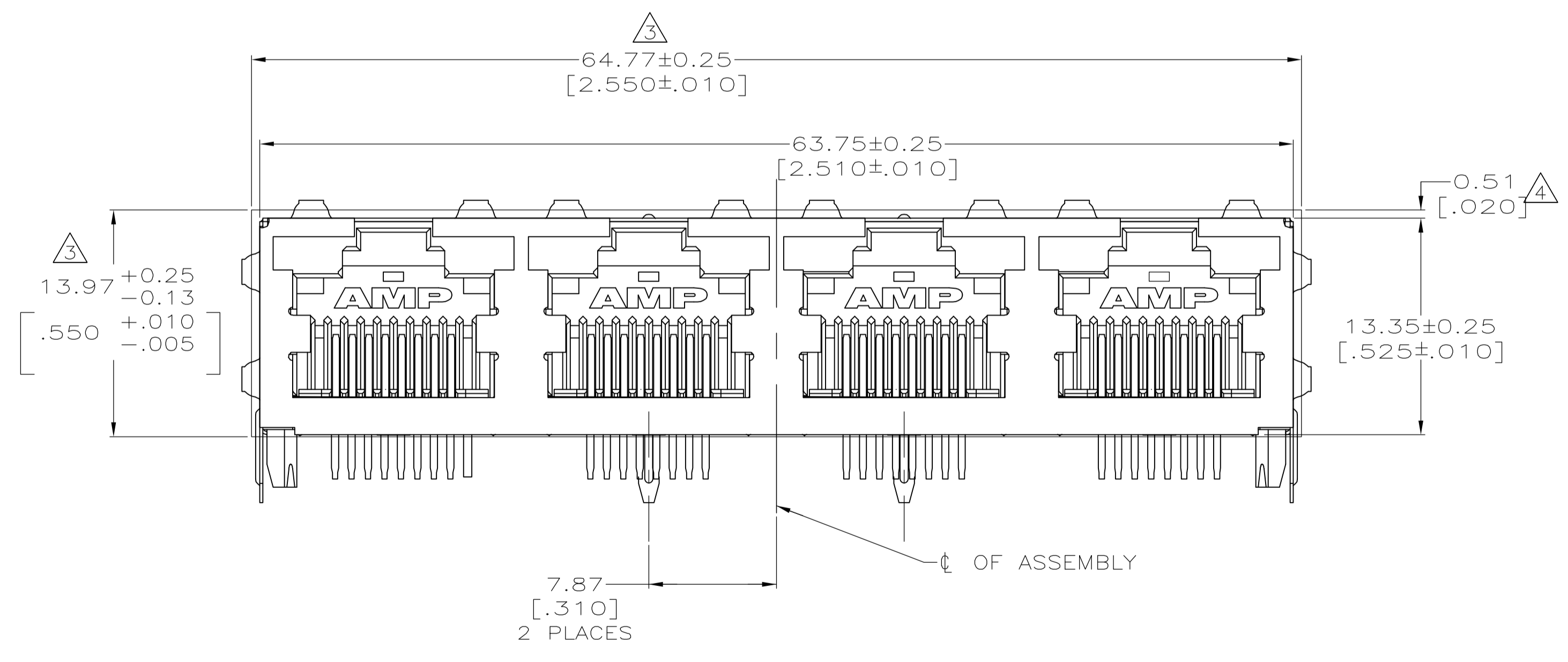
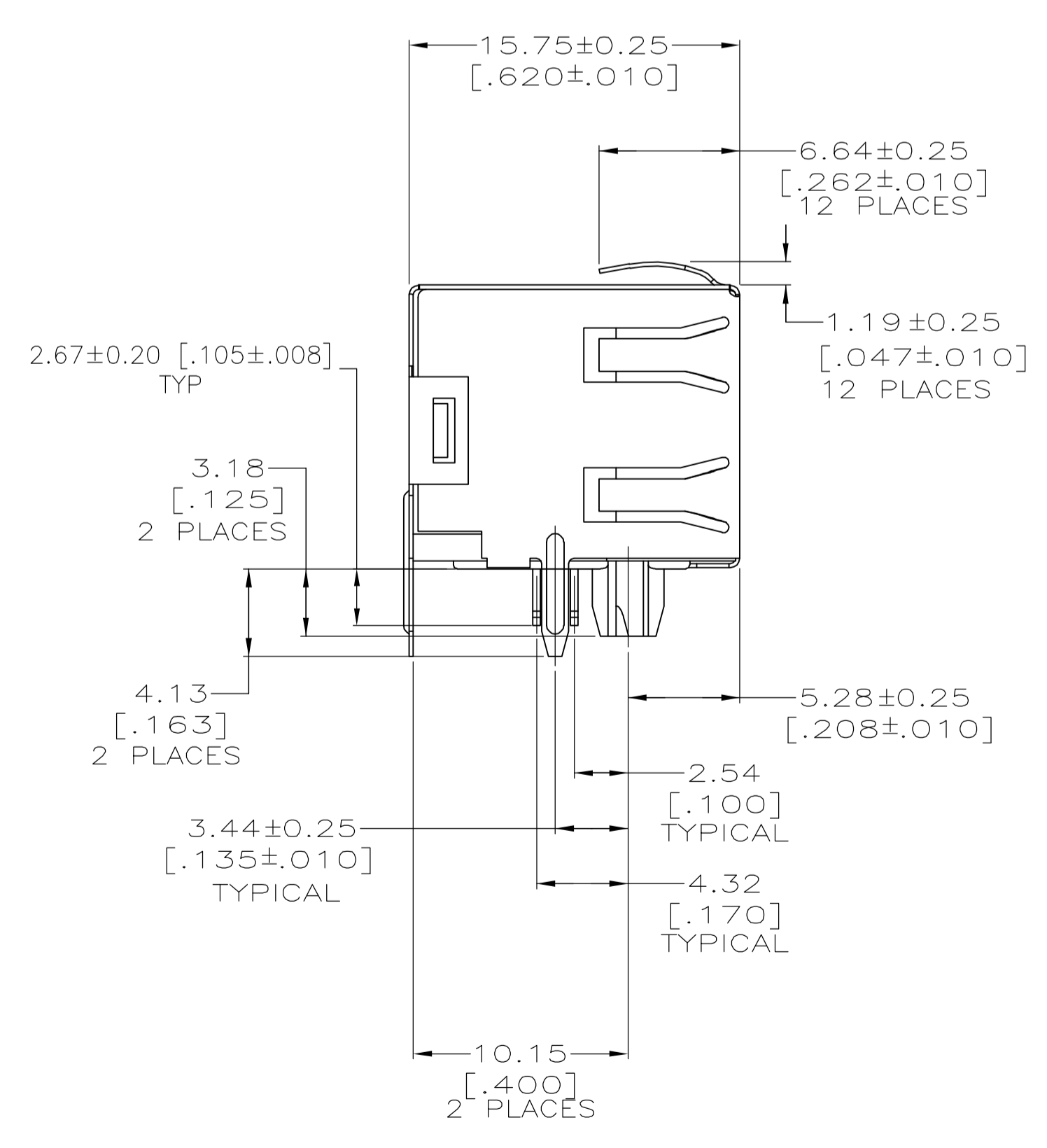


SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)



- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.  
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 0.7µm [.000030] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.  
 SHIELD - .196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.

1888630-1  
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN J. ALCORTA/L.A. MAYER 29AUG2006		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 29AUG2006		APVD S. FLICKINGER 29AUG2006	NAME 108-1163-4
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± - 4 PLC ± - ANGLES ± -		APPLICATION SPEC 114-2154		SIZE A1	CAGE CODE 00779
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		DRAWING NO 1888630	
		CUSTOMER DRAWING		SCALE 4:1	SHEET 1 OF 1